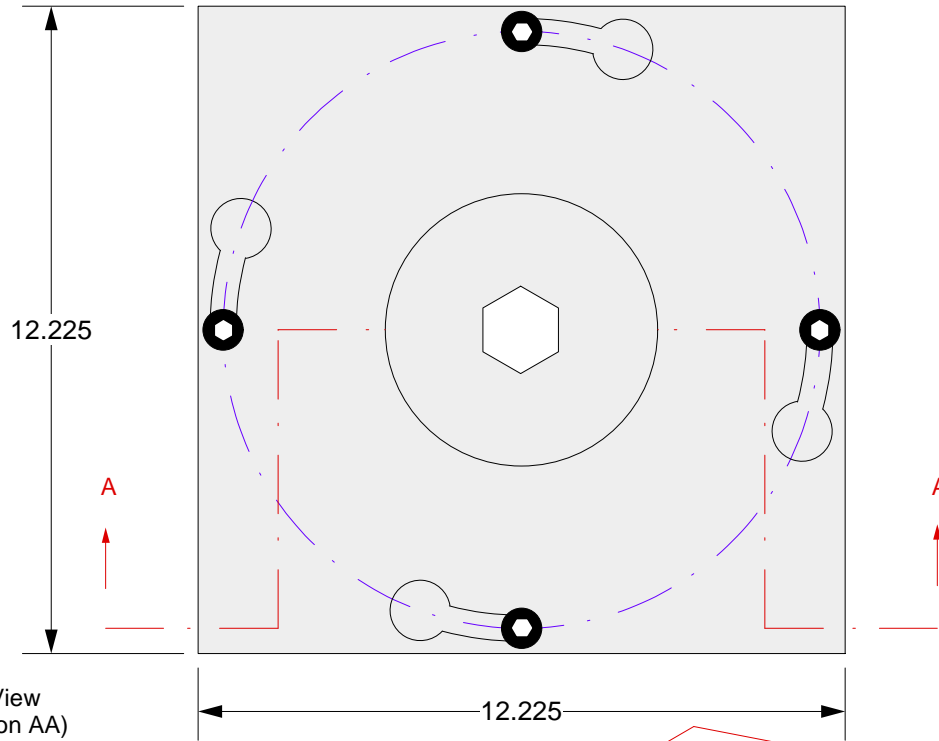
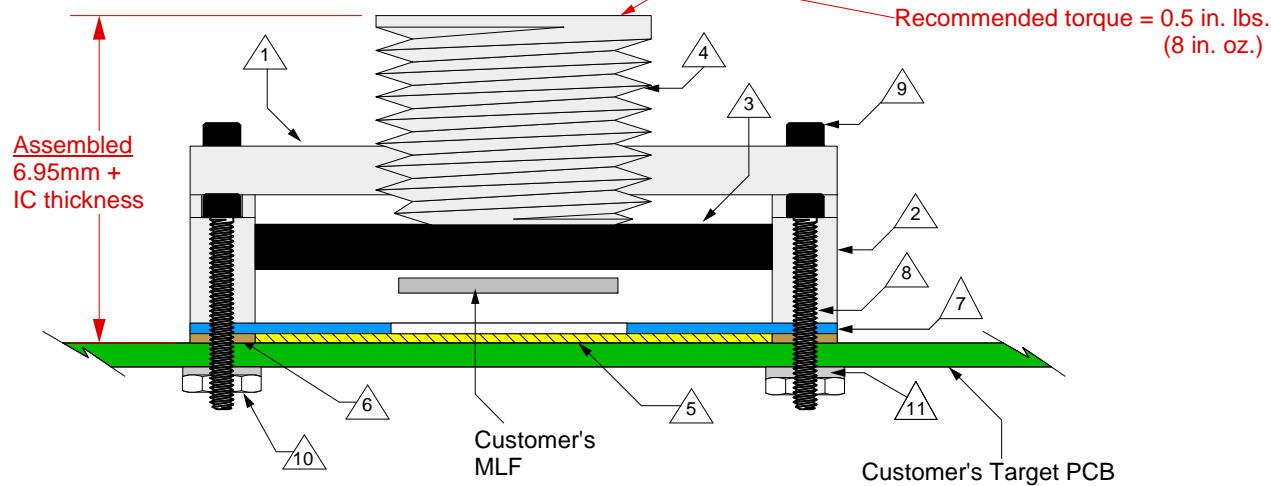


Top View



Side View
(Section AA)



GHz MLF Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- IC guide prevents over compression of elastomer
- Easily removable swivel socket lid

- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 3mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 1.5 mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 3mm.
- △ 5 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- △ 6 Elastomer Guide: Cirlex. Thickness = 0.475mm.
- △ 7 IC (MLF) Guide: Torlon 4203
- △ 8 Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread , 9.525mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- △ 11 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.

SG-MLF-7001 Drawing

Status: Released

Scale: -

Rev: K

© 2012 IRONWOOD ELECTRONICS, INC.
Tele: (800) 404-0204
www.ironwoodelectronics.com

Drawing: H. Hansen

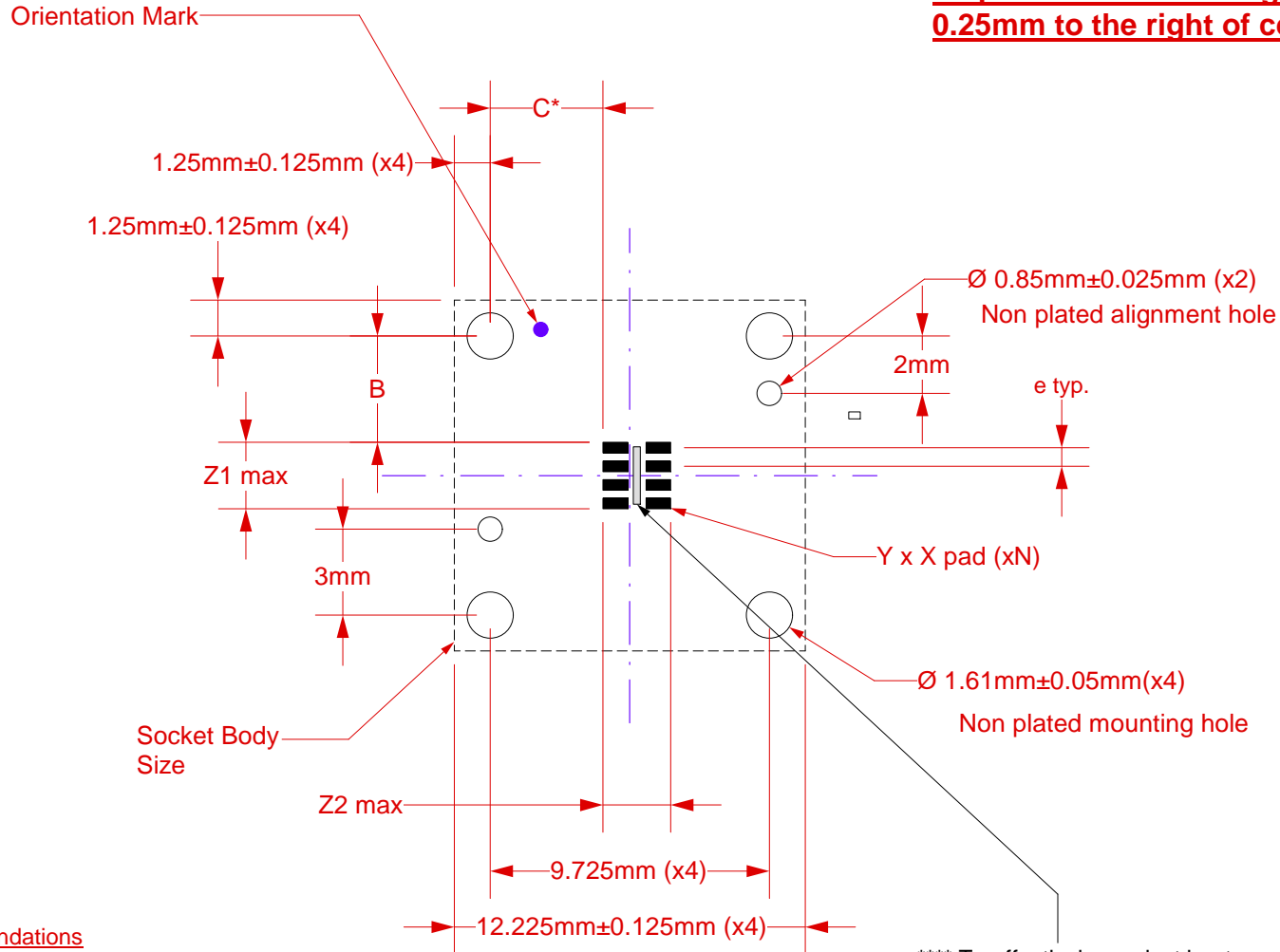
Date: 10/22/02

File: SG-MLF-7001 Dwg.mcd

Modified: 11/11/14

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: MLF pattern is not symmetrical with respect to the mounting holes. It is offset 0.25mm to the right of center.**




Target PCB Recommendations

Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

**** To effectively conduct heat away from the package a thermal pad is recommended with vias spaced 1.0 to 1.2 mm pitch and a diameter of 0.3 to 0.33 mm. Ideally 1 via for every 3 leads has been shown to work well.

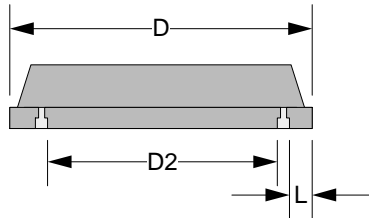
Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ unless stated otherwise.

	SG-MLF-7001 Drawing	Status: Released	Scale: 4:1	Rev: K
	© 2012 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 10/22/02
		File: SG-MLF-7001 Dwg.mcd	Modified: 11/11/14	

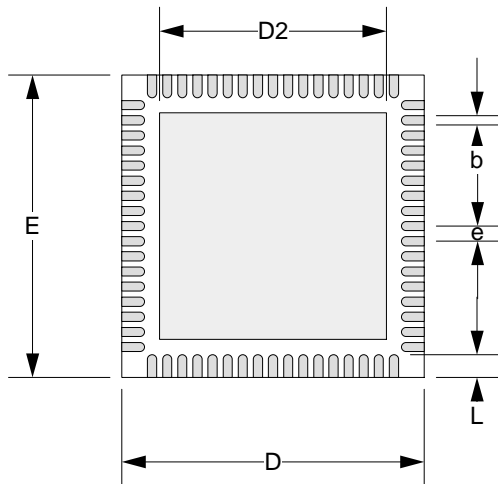
Package Code	C	B	Z1max	A1max	Z2max	A2 min	e	X	Y	N	Thermal Pad Recommendations
MLF8A	3.68	3.95	2.36	N/a	2.36	N/a	0.65	0.37	0.86	8	0.24 x 2.0
MLF8E	4.213	3.338	3.05	N/a	1.8	N/a	0.5	0.3	0.45	8	1.6 x 1.6
QFN8H	3.838	3.988	1.75	N/a	2.55	N/a	0.5	0.25	0.7	8	0.61x2.2
MLF10A	4.06	3.71	2.3	N/a	2.1	N/a	0.5	0.4	0.3	10	0.9 x 2.0


Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ unless stated otherwise.

All dimensions are in mm.



Package Code	e	D min	D max	E min	E max	b min	b max	L min	L max	D2	N
MLF8A	0.65	1.85	2.15	2.85	3.15	0.23	0.35	0.3	0.55	0.34	8
MLF8E	0.5	1.9	2.1	2.9	3.1	0.2	0.3	0.35	0.45	1.5	8
QFN8H	0.5	1.9	2.1	2.9	3.1	0.2	0.3	0.3	0.5	0.56	8
MLF10A	0.5	2.9	3.1	1.9	2.1	0.2	0.3	0.2	0.4	N/A	10



	SG-MLF-7001 Drawing © 2012 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com	Status: Released	Scale: 4:1	Rev: K
		Drawing: H. Hansen		Date: 10/22/02
		File: SG-MLF-7001 Dwg.mcd		Modified: 11/11/14